Drawing No: RPC-K-HTS-0002 /10

Date: 2025. 3. 18

# Data sheet

Title: FIXED THICK FILM CHIP RESISTORS;
RECTANGULAR TYPE AND ANTI SURGE

Style: RPC16, 20, 32, 35, 50, 63

# RoHS COMPLIANCE ITEM Halogen and Antimony Free

Note: •Stock conditions

Temperature:  $+5^{\circ}\text{C} \sim +35^{\circ}\text{C}$ Relative humidity:  $25\% \sim 75\%$ 

The period of guarantee: Within 2 year from shipment by the company.

Solderability shall be satisfied.

- Product specification contained in this data sheet are subject to change at any time without notice
- •If you have any questions or a Purchasing Specification for any quality agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya KAMAYA OHM

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FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND ANTI SURGE

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#### 1. Scope

1.1 This data sheet covers the detail requirements for fixed thick film chip resistors; rectangular type & anti surge, style of RPC16, 20, 32, 35, 50, 63.

# 1.2 Applicable documents

JIS C 5201-1: 2011, JIS C 5201-8: 2014, JIS C 5201-8-1: 2014 IEC60115-1: 2008, IEC60115-8: 2014, IEC60115-8-1: 2014 EIAJ RC-2134C-2010

# 2. Classification

Type designation shall be the following form.

(Example)

RPC	32	475	J	TP
1	2	3	4	5
Sty	/le			

1 Fixed thick film chip resistors; rectangular type and anti surge

Style

2 Size

3 Rated resistance

475 E24 Series, 3 digit, Ex. 475> 4.7MΩ	
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4 Tolerance on rated resistance

J	±5%
K	±10%
М	±20%

5 Packaging form

_		
	TP	Paper taping
	TE	Embossed taping

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# 3. Rating

3.1 The ratings shall be in accordance with Table-1.

Table-1

Style	Rated dissipation (W)	Temperature coefficient of resistance ( 10 <sup>-6</sup> / °C)	Rated resistance range(Ω)	Preferred number series for resistors	Tolerance on rated resistance
RPC16	0.25	±100	10~1M	E24	1(+50/)
KECIO	0.23	±200	1.0~9.1	C2 <del>4</del>	J(±5%)
		±200	1.1M~22M		
RPC20	0.25	±100	1.0~1M	E24	J(±5%), K(±10%), M(±20%)
		±200	0.27~0.91		
		±200	1.1M~22M		
RPC32	0.33	±100	1.0~1M	E24	J(±5%), K(±10%), M(±20%)
		±200	0.27~0.91		
		±200	1.1M~22M		
RPC35	0.5	±100	1.0~1M	E24	J(±5%), K(±10%), M(±20%)
		±200	0.27~0.91		
		±200	1.1M~22M		
RPC50	0.75	±100	1.0~1M	E24	J(±5%), K(±10%), M(±20%)
		±200	0.27~0.91		
		±200	1.1M~22M		
RPC63	1.0	±100	1.0~1M	E24	J(±5%), K(±10%), M(±20%)
		±200	0.27~0.91		

Style	Limiting element voltage (V)	Insulation voltage (V)	Category temperature range (°C)
RPC16	150	150	
RPC20	150		
RPC32			EE 14EE
RPC35	200	500	<i>–</i> 55∼+155
RPC50	200		
RPC63			

3.2 Climatic category

55/155/56 Lower category temperature - 55 °C

Upper category temperature +155 °C

Duration of the damp heat, steady state test 56days

3.3 Stability class

5% Limits for change of resistance:

 $\begin{array}{ll} -\text{for long-term tests} & \pm (5\% + 0.1\Omega) \\ -\text{for short-term tests} & \pm (1\% + 0.05\Omega) \end{array}$ 

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#### 3.4 Derating

The derated values of dissipation at temperature in excess of 70 °C shall be as indicated by the following curve.

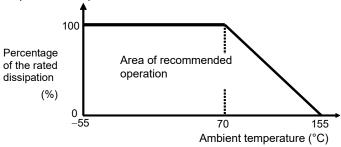


Figure-1 Derating curve

# 3.5 Rated voltage

d. c. or a. c. r. m. s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

$$E = \sqrt{P \cdot R}$$

E: Rated voltage (V)

P: Rated dissipation (W)

R: Rated resistance ( $\Omega$ )

Limiting element voltage can only be applied to resistors when the resistance value is equal to or higher than the critical resistance value.

At high value of resistance, the rated voltage may not be applicable.

# 4. Packaging form

The standard packaging form shall be in accordance with Table-2.

# Table-2

	Symbol	Pa	ckaging form	Standard packaging quantity / units	Application	
	TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	RPC16, 20, 32	
	TE Embassed tening		8mm width, 4mm pitches	4.000 pag	RPC35	
	I E Embossed ta	TE	Embossed taping	12mm width, 4mm pitches	4,000 pcs.	RPC50, 63

I Init: mm

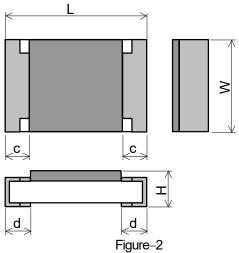
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#### 5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure-2 and Table-3.



Figure\_2 Table\_3

	Table_3				Offic Hilli
Style	L	W	Н	С	d
RPC16	1.6±0.1	0.8 +0.15 -0.05	0.45±0.10	0.3±0.2	0.3±0.1
RPC20	$2.0 \pm 0.1$	1.25 ± 0.10	0.55 ± 0.10	$0.3 \pm 0.2$	$0.4 \pm 0.2$
RPC32	$3.1 \pm 0.1$	1.6 ± 0.15	$0.55 \pm 0.10$	$0.3 \pm 0.2$	$0.5 \pm 0.25$
RPC35	$3.1 \pm 0.15$	$2.5 \pm 0.15$	$0.55 \pm 0.15$	$0.3 \pm 0.2$	$0.5 \pm 0.25$
RPC50	$5.0 \pm 0.15$	$2.5 \pm 0.15$	$0.55 \pm 0.15$	$0.3 \pm 0.15$	$0.6 \pm 0.2$
RPC63	$6.3 \pm 0.15$	$3.2 \pm 0.15$	$0.55 \pm 0.15$	$0.3 \pm 0.15$	$0.6 \pm 0.2$

# 5.2 Net weight (Reference)

Style	Net weight(mg)
RPC16	2
RPC20	5
RPC32	9
RPC35	16
RPC50	25
RPC63	40

# 6. Marking

The Rated resistance shall be marked in 3 digits (E24) and marked on over coat side.

Marking example	Contents	Application
123	12×10 <sup>3</sup> $[\Omega] \rightarrow$ 12 $[k\Omega]$	E24
2R2	2.2 [Ω]	E24

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#### 7. Performance

7.1 The standard condition for tests shall be in accordance with Sub-clause 4.2, JIS C 5201–1: 2011.

7.2 The performance shall be satisfied in Table-4.

Table-4(1)

No.	Test items	Condition of test (JIS C 5201–1)	Performance requirements
1	Visual examination	Sub-clause 4.4.1	As in 4.4.1
		Checked by visual examination.	The marking shall be legible, as
			checked by visual examination.
2	Dimension	Sub-clause 4.4.2	As specified in Table-3 of this
			specification.
	Resistance	Sub-clause 4.5	As in 4.5.2
			The resistance value shall
			correspond with the rated resistance
			taking into account the specified
			tolerance.
3	Voltage proof	Sub-clause 4.7	
		Method: 4.6.1.4(See Figure–5)	No breakdown or flash over
		Test voltage: Alternating voltage with a peak	
		value of 1.42 times the insulation	
		voltage.	
		Duration: 60 s ± 5 s	
		Insulation resistance	R≥1GΩ
		Test voltage: Insulation voltage	
		Duration: 1 min.	
4	Solderability	Sub-clause 4.17	As in 4.17.4.5
		Without ageing	The terminations shall be covered
		Flux: The resistors shall be immersed in a	with a smooth and bright solder
		non-activated soldering flux for 2s.	coating.
		Bath temperature: 235 °C ± 5 °C	
		Immersion time: 2 s ± 0.5 s	
5	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure–3	
	O made and	Sub-clause 4.13	
	Overload	The applied voltage shall be 2.5 times the rated	
	(in the mounted state)	voltage or twice the limiting element voltage,	
		whichever is the less severe.	
		Duration: 2 s	No visible demage
		Visual examination	No visible damage
	Solvent resistance of the	Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
	marking	Sub-clause 4.30	Legible marking
	mainig	Solvent: 2–propanol	
		Solvent temperature: 23 °C ± 5 °C	
		Method 1	
		Rubbing material: cotton wool	
		Without recovery	

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Table-4(2)

		1able-4(2)	
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
6	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure-4	
	Bound strength of the end	Sub-clause 4.33	
	face plating	Bent value: 3 mm (3225 size max.)	
		1 mm (5025 size min.)	
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
	Final measurements	Sub-clause 4.33.6	No visible damage
		Visual examination	
7	Resistance to soldering heat	Sub-clause 4.18	
	_	Solder temperature: 260 °C ± 5 °C	
		Immersion time: 10 s ± 0.5 s	
		Visual examination	As in 4.18.3.4
			No sign of damage such as cracks.
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
	Component solvent	Sub-clause 4.29	, ,
	resistance	Solvent: 2-propanol	
		Solvent temperature: 23 °C ± 5 °C	
		Method 2	
		Recovery: 48 h	
		Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
8	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure–3	
	Adhesion	Sub-clause 4.32	
		Force: 5 N	
		Duration: 10 s ± 1 s	
		Visual examination	
	Rapid change temperature	Sub-clause 4.19	No visible damage
		Lower category temperature:-55 °C	
		Upper category temperature:+155 °C	
		Duration of exposure at each temperature:	
		30 min.	
		Number of cycles: 5 cycles.	Nicola Salla I anno anno
		Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$

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# Table-4(3)

Test items	Condition of test (JIS C 5201–1)	Performance requirements
Climatic sequence  –Dry heat	Sub-clause 4.23 Sub-clause 4.23.2	
,	Test temperature: +155 °C Duration: 16 h	
-Damp heat, cycle Sub-clause 4.23.3		
	Test method: 2	
First cycle		
-Cold		
Dames hast such		
Remaining cycle		
–D.C. load		
<i>B.</i> 0. load		
		No visible damage
	Resistance	$\Delta R \le \pm (5\% + 0.1\Omega)$
Mounting	Sub-clause 4.31	
	Substrate material: Epoxide woven glass	
	(RPC63 may use Alumina substrate.)	
	Test substrate: Figure–3	
Endurance at 70 °C	Sub-clause 4.25.1	
Duration: 1000 h The voltage shall be applied in cycles of 1.5 h on and 0.5 h.		
		No visible damage
		$\Delta R \le \pm (5\% + 0.1\Omega)$
	Climatic sequence  -Dry heat  -Damp heat, cycle (12+12hour cycle) First cycle  -Cold  -Damp heat, cycle (12+12hour cycle) Remaining cycle  -D.C. load	Climatic sequence  -Dry heat  Sub-clause 4.23 Sub-clause 4.23.2 Test temperature: +155 °C Duration: 16 h Sub-clause 4.23.3 Test method: 2 Test temperature: 55 °C [Severity(2)] Sub-clause 4.23.4  -Cold  -Damp heat, cycle (12+12hour cycle) Remaining cycle  Remaining cycle  -D.C. load  Test temperature: 55 °C [Severity (2)] Number of cycles: 5 cycles Sub-clause 4.23.7  The applied voltage shall be the rated voltage or the limiting element voltage whichever is the smaller. Duration: 1 min. Visual examination Resistance  Mounting  Mounting  Sub-clause 4.31 Substrate material: Epoxide woven glass (RPC63 may use Alumina substrate.) Test substrate: Figure-3 Sub-clause 4.25.1 Ambient temperature: 70 °C ± 2 °C Duration: 1000 h The voltage shall be applied in cycles of 1.5 h

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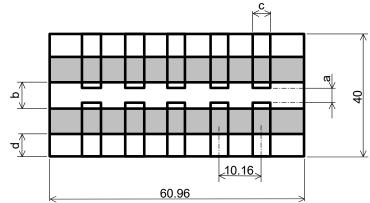
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Table-4(4)

No	Test items Condition of test (JIS C 5201–1) Performance requirements				
		,	renormance requirements		
11	Mounting	Sub-clause 4.31			
		Substrate material: Epoxide woven glass			
	Variation of resistance with	Test substrate: Figure–3	As in Table 1		
		Sub-clause 4.8	As in Table–1		
		-55 °C / +20 °C			
		+20 °C / +155°C			
12	Mounting	Sub-clause 4.31			
		Substrate material: Epoxide woven glass			
	5	Test substrate: Figure–3			
	Damp heat, steady state	Sub-clause 4.24			
		Ambient temperature: 40 °C ± 2 °C			
		Relative humidity: $93^{+2}_{-3}$ %			
		a) 1st group: without voltage applied.			
		b) 2nd group: The d. c. voltage shall be applied			
		continuously.			
		The voltage shall be accordance with			
		Sub-clause 4.24.2.1 b). without polarizing			
		voltage [4.24.2.1, c)]			
		Visual examination	No visible damage Legible marking		
		B : 4	$\Delta R \le \pm (5\% + 0.1\Omega)$		
40	5: (1.6.3)	Resistance	,		
13	Dimensions (detail)	Sub-clause 4.4.3	As in Table–3		
	NA - vertire -				
		Sub-clause 4.31			
		Substrate material: Epoxide woven glass			
	Test substrate: Figure–3 Endurance at upper category Sub-clause 4 25 3				
, o i cab diade		Sub-clause 4.25.3			
	Duration: 1000 h Examination at 48 h, 500 h and 1000 h:				
			No visible damage		
		Visual examination	$\Delta R \le \pm (5\% + 0.1\Omega)$		
		Resistance	$\triangle (1 \setminus 2 \perp (0 \setminus 0 \setminus 1) \setminus (0 \setminus 0 \setminus 1))$		

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# 8. Test substrate



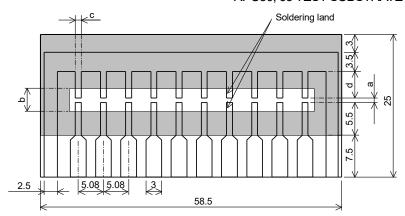
#### Unit: mm

:Copper clad

:Solder resist

Style	а	b	С	d
RPC50	4.0	7.5	2.0	7.5
RPC63	5.0	9.0	4.5	7.5

# RPC50, 63 TEST SUBSTRATE



# Unit: mm

:Copper clad

:Solder resist

Style	а	b	С	d
RPC20	1.2	4.0	1.5	4.3
RPC32	2.1	3.9	1.7	3.4
RPC35	2.2	5.0	2.9	3.3

# RPC20,32,35 TEST SUBSTRATE

Figure–3(1)

# Remark 1). Material: Epoxide woven glass

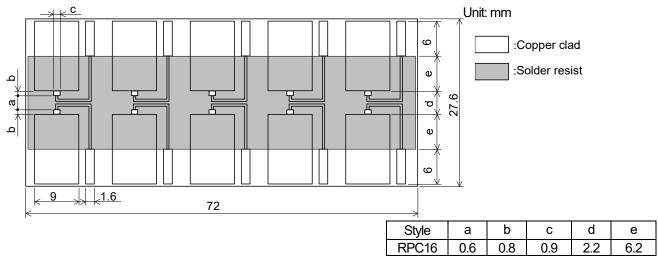
Thickness: 1.6mm Thickness of copper clad: 0.035mm

2). In the case of connection by connector, the connecting terminals are gold plated. However, the plating is not necessary when the connection is made by soldering.

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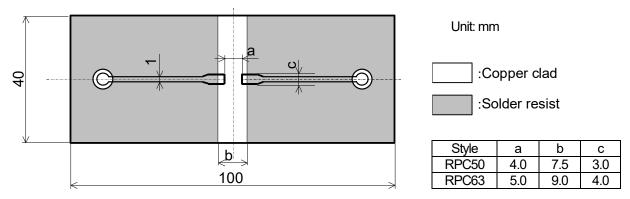
**RPC16 TEST SUBSTRATE** 

Figure-3(2)

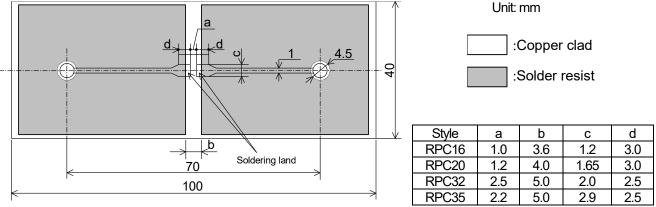
Remark 1). Material: Epoxide woven glass

Thickness: 1.6mm Thickness of copper clad: 0.07mm

2). In the case of connection by connector, the connecting terminals are gold plated. However, the plating is not necessary when the connection is made by soldering.



RPC50, 63 BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

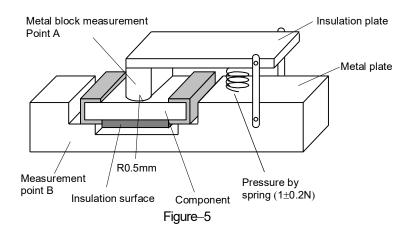


Remark 1). Material: Epoxide woven glass

Thickness: 1.6mm Thickness of copper clad: 0.035mm RPC16,20,32,35 BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE Figure-4

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# 9. Taping

- 9.1 Applicable documents JIS C 0806–3: 2014, EIAJ ET–7200C: 2010
- 9.2 Taping dimensions
- 9.2.1 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-6 and Table-5.

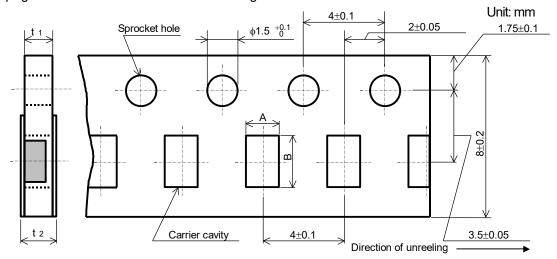


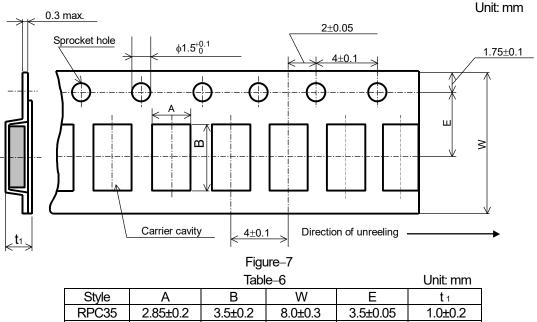
Figure-6

	Unit: mm			
Style	Α	В	<b>t</b> 1	t 2
RPC16	1.15 ± 0.15	1.9 ± 0.2	$0.6 \pm 0.1$	0.8max.
RPC20	1.65±0.15	2.5±0.2	0.8±0.1	1.0000
RPC32	2.00±0.15	3.6±0.2	U.0±U.1	1.0max.

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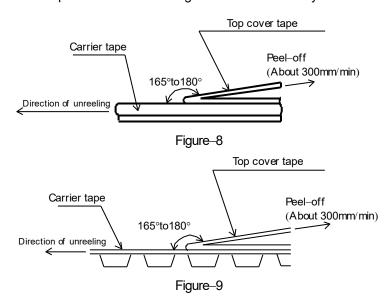
Drawing No:

# 9.2.2 Embossed taping dimensions shall be in accordance with Figure-7 and Table-6.



	O				
Style	Α	В	W	E	t 1
RPC35	2.85±0.2	3.5±0.2	8.0±0.3	3.5±0.05	1.0±0.2
RPC50	3.1±0.2	5.5±0.2	12.0±0.3	5.5±0.05	1.1±0.15
RPC63	3.6±0.2	6.9±0.2	12.0±0.3	5.5±0.05	1.1±0.15

- 1). The cover tapes shall not cover the sprocket holes.
- Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following RPC16, 20, 32: Figure-8, RPC35, 50, 63: Figure-9.
- 6). When the tape is bent with the minimum radius for RPC16, 20, 32, 35: 25 mm, or RPC50, 63: 30 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing. The maximum number of missing components shall be one or 0.1%, whichever is greater.
- 8). The resistors shall be faced to upward at the over coating side in the carrier cavity.



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#### 9.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure–10 and Table–7. Plastic reel (Based on EIAJ ET–7200C)

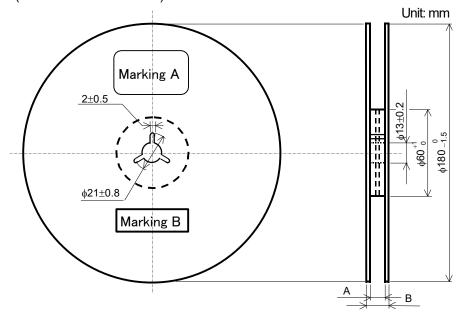
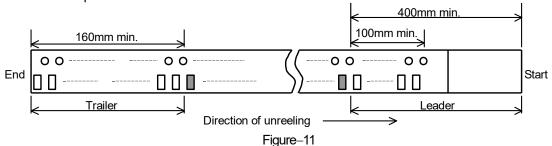


Figure-10

Table–7			Unit: mm
Style	A B		Note
RPC16,20,32,35	9 +1.0	11.4±1.0	Injection molding
NFC 10,20,32,33	9 0	13±1.0	Vacuum forming
RPC50,63	13 <sup>+1.0</sup>	17±1.0	Vacuum forming

Note: Marking label shall be marked on a place of Marking A or two place of Marking A and B.

# 9.4 Leader and trailer tape.



# 10. Marking on package

The label of a minimum package shall be legibly marked with follows.

# 10.1 Marking A

- (1) Classification (Style, Rated resistance, Tolerance on rated resistance, Packaging form)
- (2) Quantity (3) Lot number (4) Manufacturer's name or trade mark (5) Others
- 10.2 Marking B (KAMAYA Control label)